

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-16 (cancelled)

17. (currently amended) A surface treatment process, comprising: providing a ~~hydrophillic~~ copper hydrophilic surface; polishing said surface with a slurry that comprises a suspension of abrasive particles in deionized water and TMAH, whereby said surface is rendered hydrophobic; and thereby causing all of said abrasive particles to be removed when said surface is rinsed in deionized water, said abrasive particles having a mean diameter of between about 1 and 10,000 microns, wherein the TMAH has a concentration in said deionized water of between about 2% and 20%.

18. (cancelled)

19. (original) The process described in claim 17 wherein said abrasive particles are selected from the group consisting of alumina and silica.

20. (cancelled)

21. (cancelled)

22. (previously presented) A surface treatment process, comprising: providing a ~~hydrophillic~~ copper hydrophilic surface; polishing said surface with a slurry that comprises a suspension of abrasive particles in deionized water and TBAH, whereby said surface is rendered hydrophobic; and thereby causing all of said abrasive particles to be removed when said surface is rinsed in deionized water, said abrasive particles having a mean diameter of between about 1 and 10,000 microns, wherein the TBAH has a concentration in said deionized water of between about 2 and 20%.

23. (cancelled)

24. (original) The process described in claim 22 wherein said abrasive particles are selected from the group consisting of alumina and silica.

25-30 (cancelled)